



Board Characteristics - 4 LAYER BOARD

1. $T_g > 170C$
2. Minimum trace width: 0.005" and clearance: 0.005"
4. 1 oz copper for all layers
5. Electroless Nickel Immersion Gold plating, with min. Ni: 2.5-5 um; Au: 0.05-0.2 um.
6. Board Thickness: 0.062
7. FHS tolerances: +/- 0.003 unless specified otherwise.
8. $Z_c=50 \text{ Ohm}$, $Z_d=100 \text{ Ohm}$ Controlled Impedance on 5-mil traces
9. Apply Solder Mask over bare copper.
10. Remove all non-functional inner layer pads for pins and vias.
11. Do not increase size of thermal pads and associated spoke connections on holes.

BOARD'S DRILL SCHEDULE

DRILL SYMBOL	DRILL SIZE	COUNT	PLATED	Tolerance	COMMENT
○	.0091	5	YES	---	
⊞	.035	16	YES	---	
⊕	.041	2	YES	---	
⊞	.052	89	YES	---	
⊖	.066	4	YES	---	
⊞	.11811024	4	NO	---	
⊕	.12	8	YES	---	
□	.12795276	4	YES	---	

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE: FRACTIONS DECIMALS ANGLES . XX . XXX DO NOT SCALE DRAWING			CONTRACT NO.		UNIVERSITY OF CHICAGO ELECTRONICS DEVELOPMENT GROUP				
			APPROVALS					DATE	
TREATMENT			DRAWN M. Bogdan		TITLE DAMIC - CBB Specification Drawing				
FINISH			CHECKED M. Bogdan		SIZE B		FSCM NO.	DWG. NO. 2992-B	REV. A
SIMILAR TO			ACT. WT	CALC WT	ISSUED		SCALE 1/2		SHEET